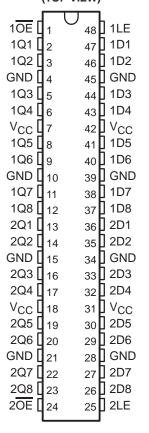
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- State-of-the-Art Advanced BiCMOS Technology (ABT) Widebus™ Design for 2.5-V and 3.3-V Operation and Low Static **Power Dissipation**
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V_{CC})
- **Typical V_{OLP} (Output Ground Bounce)** $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- High Drive (-24/24 mA at 2.5-V and -32/64 mA at 3.3-V V_{CC})
- **Power Off Disables Outputs, Permitting Live Insertion**
- **High-Impedance State During Power Up** and Power Down Prevents Driver Conflict
- Uses Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- **Auto3-State Eliminates Bus Current** Loading When Output Exceeds V_{CC} + 0.5 V
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model; and Exceeds 1000 V **Using Charged-Device Model, Robotic** Method
- Flow-Through Architecture Facilitates **Printed Circuit Board Layout**
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- **Package Options Include Plastic Shrink** Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Package

SN54ALVTH16373 . . . WD PACKAGE SN74ALVTH16373... DGG, DGV, OR DL PACKAGE (TOP VIEW)



description

The 'ALVTH16373 devices are 16-bit transparent D-type latches with 3-state outputs designed for 2.5-V or 3.3-V $V_{
m CC}$ operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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description (continued)

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

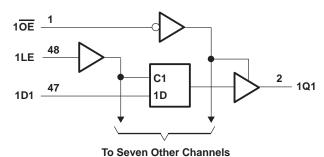
The SN54ALVTH16373 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALVTH16373 is characterized for operation from –40°C to 85°C.

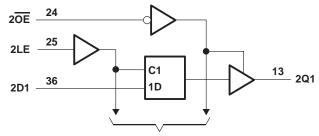
FUNCTION TABLE (each 8-bit section)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	X	Χ	Z



logic diagram (positive logic)





To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}).5 V to 4.6 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V _O (see Note 1)	–0.5 V to 7 V
Output current in the low state, IO: SN54ALVTH16373	96 mA
SN74ALVTH16373	
Output current in the high state, IO: SN54ALVTH16373	–48 mA
SN74ALVTH16373	
Input clamp current, I _{IK} (V _I < 0)	−50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T _{stq} 68	5°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions, V_{CC} = 2.5 V \pm 0.2 V (see Note 3)

			SN54	ALVTH1	6373	SN74	ALVTH1	6373	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Vcc	Supply voltage		2.3		2.7	2.3		2.7	V
VIH	High-level input voltage	1.7			1.7			V	
V _{IL}	Low-level input voltage		4	0.7			0.7	V	
VI	Input voltage	0	VCC	5.5	0	VCC	5.5	V	
IOH	High-level output current			,0	-6			-8	mA
la	Low-level output current			Ç	6			8	mΑ
lor	Low-level output current; current duty cycle ≤ 50%; f ≥ 1 kHz		5	5	18			24	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	87		10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200			200			μs/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



^{2.} The package thermal impedance is calculated in accordance with JESD 51.

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recommended operating conditions, $V_{\mbox{\footnotesize{CC}}}$ = 3.3 V \pm 0.3 V (see Note 3)

			SN54	ALVTH1	6373	SN74	ALVTH1	6373	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNII
VCC	Supply voltage		3		3.6	3		3.6	V
VIH	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V	
VI	Input voltage	0	Vcc	5.5	0	VCC	5.5	V	
IOH	High-level output current		Q	-24			-32	mA	
la	Low-level output current			(0)	24			32	mA
lOL	Low-level output current; current duty cycle \leq 50%; f \geq 1 kHz		4	\tilde{Q}	48			64	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	8		10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate	·	200			200			μs/V
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted)

	DAMETED	TEST O	ONDITIONS	SN54	ALVTH1	6373	SN74	ALVTH1	6373	LINUT
PA	ARAMETER	TEST	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK		$V_{CC} = 2.3 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	$I_{OH} = -100 \mu A$	V _{CC} -0.	2		V _{CC} -0	.2		
VOH		V _{CC} = 2.3 V	I _{OH} = -6 mA	1.8						V
		vCC = 2.3 v	I _{OH} = -8 mA				1.8			
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OL} = 100 μA			0.2			0.2	
			I _{OL} = 6 mA			0.4				
VOL		V _{CC} = 2.3 V	$I_{OL} = 8 \text{ mA}$						0.4	V
	V(C) = 2.5 V	I _{OL} = 18 mA			0.5					
			I _{OL} = 24 mA						0.5	
	Control inputs	$V_{CC} = 2.7 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1	
	Control inputs	$V_{CC} = 0 \text{ or } 2.7 \text{ V},$	V _I = 5.5 V			<u>\$</u> 10			10	
II			V _I = 5.5 V		, i	10			10	μΑ
	Data inputs	$V_{CC} = 2.7 \text{ V}$	VI = VCC		77	1			1	
			V _I = 0		1	- 5			– 5	
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V		2				±100	μΑ
I _{BHL} ‡		$V_{CC} = 2.3 \text{ V},$	V _I = 0.7 V		115			115		μΑ
IBHH§		$V_{CC} = 2.3 \text{ V},$	V _I = 1.7 V	Q	-10			-10		μΑ
I _{BHLO}	¶	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	300			300			μΑ
Івннс) [#]	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	-300			-300			μΑ
{IEX}		$V{CC} = 2.3 \text{ V},$	V _O = 5.5 V			125			125	μΑ
IOZ(Pl	J/PD)☆	$V_{CC} \le 1.2 \text{ V}, V_{O} = 0.5 \text{ V}$ $V_{I} = \text{GND or } V_{CC}, \overline{\text{OE}} = 0.5 \text{ V}$	/ to V _{CC} , = don't care			±100			±100	μΑ
lozh		V _{CC} = 2.7 V	$V_0 = 2.3 \text{ V},$ $V_1 = 0.7 \text{ V or } 1.7 \text{ V}$			5			5	μΑ
lozL		V _{CC} = 2.7 V	$V_O = 0.5 \text{ V},$ $V_I = 0.7 \text{ V or } 1.7 \text{ V}$			-5			-5	μΑ
		V _{CC} = 2.7 V,	Outputs high		0.04	0.1		0.04	0.1	
Icc			Outputs low	1	2.3	4.5		2.3	4.5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.04	0.1		0.04	0.1	
Ci		V _{CC} = 2.5 V,	V _I = 2.5 V or 0	1	3.5			3.5		pF
Co		V _{CC} = 2.5 V,	V _O = 2.5 V or 0		6			6		pF

[†] All typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

[¶] An external driver must source at least IBHLO to switch this node from low to high.

[#]An external driver must sink at least IBHHO to switch this node from high to low.

Current into an output in the high state when VO > VCC

[★]High-impedance state during power up or power down

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

PARAMETER		TEST O	ONDITIONS	SN54	ALVTH1	6373	SN74	ALVTH1	6373	LINUT
PA	RAMEIER	l lesi c	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP†	MAX	UNIT
VIK		V _{CC} = 3 V,	I _I = -18 mA			-1.2			-1.2	V
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		V _{CC} -0	.2		
Vон		V 2.V	I _{OH} = -24 mA	2						V
		VCC = 3 V	I _{OH} = -32 mA				2			
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OL} = 100 μA			0.2			0.2	
			I _{OL} = 16 mA						0.4	
V _{OL}			I _{OL} = 24 mA			0.5				V
VOL		V _{CC} = 3 V	$I_{OL} = 32 \text{ mA}$						0.5	V
			$I_{OL} = 48 \text{ mA}$			0.55				
	_		$I_{OL} = 64 \text{ mA}$						0.55	
	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1	
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V		Š	10			10	
Ц			V _I = 5.5 V		77	10			10	μΑ
	Data inputs	V _{CC} = 3.6 V	VI = VCC		1	1			1	
			V _I = 0		2	- 5			– 5	
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V	0					±100	μΑ
I _{BHL} ‡		$V_{CC} = 3 V$,	V _I = 0.8 V	75			75			μΑ
I _{BHH} §		V _{CC} = 3 V,	V _I = 2 V	-75			-75			μΑ
^I BHLO	¶	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	500			500			μΑ
Івнно	#	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	-500			-500			μΑ
I _{EX}		$V_{CC} = 3 V$,	V _O = 5.5 V			125			125	μΑ
loz(PL	J/PD)☆	$V_{CC} \le 1.2 \text{ V}, V_{O} = \underline{0.5} \text{ V}$ $V_{I} = \text{GND or } V_{CC}, \overline{OE} = \underline{0.5} \text{ V}$	V to V _{CC} , = don't care			±100			±100	μΑ
lozh		V _{CC} = 3.6 V	V _O = 3 V,			5			5	μΑ
			V _I = 0.8 V or 2 V							
lozL		V _{CC} = 3.6 V	$V_0 = 0.5 \text{ V},$			-5			-5	μΑ
-			V _I = 0.8 V or 2 V	┼			<u> </u>		0.4	
		$V_{CC} = 3.6 \text{ V},$	Outputs high	₩	0.07	0.1		0.07	0.1	
ICC		$I_O = 0,$ $V_I = V_{CC}$ or GND	Outputs low	+	3.2	5.5		3.2	5	mA
<u> </u>			Outputs disabled	+	0.07	0.1		0.07	0.1	
∆lcc□		V _{CC} = 3 V to 3.6 V, One Other inputs at V _{CC} or	e input at V _{CC} – 0.6 V, GND			0.4			0.4	mA
C _i		$V_{CC} = 3.3 \text{ V},$	$V_{I} = 3.3 \text{ V or } 0$		3.5			3.5		pF
Co		V _{CC} = 3.3 V,	V _O = 3.3 V or 0		6			6		pF

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[□]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

 $[\]P$ An external driver must source at least $I_{\mbox{\footnotesize{BHLO}}}$ to switch this node from low to high.

[#] An external driver must sink at least IBHHO to switch this node from high to low.

Current into an output in the high state when VO > VCC

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timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

			SN54ALVTH16373	SN74ALVTH	SN74ALVTH16373		
			MIN MAX	MIN	MAX	UNIT	
t _W	Pulse duration, LE high		1.5	1.5		ns	
	Octor force data to force LE	Data high	1.1,0	1			
^l su	t _{SU} Setup time, data before LE↓	Data low	1.6	1.5		ns	
+.	ti Hold time data after LE	Data high	S1	0.9		ns	
t _h	noid time, data after LE↓	ld time, data after LE↓ Data low				115	

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

			SN54ALVT	H16373	SN74ALVT	H16373	UNIT
			MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, LE high		1.5	TY.	1.5		ns
	Catua time data hafara I E	Data high	1.5,		1.4		ns
t _{su}	Setup time, data before LE↓	Data low	(I)		0.9		115
t _h Hold time, data after LE	Hold time data after I E	Data high	Q1		0.9		ns
	Hold time, data after LE↓	Data low	1.5		1.4		115

switching characteristics over recommended operating free-air temperature range, C_L = 30 pF, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	SN54ALVTH16373	SN74ALVTI	H16373	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN MAX	MIN	MAX	UNII	
^t PLH		Q	1 3.4	1	3.3	ns	
t _{PHL}	D	Q	1 4.3	1	4.2	115	
^t PLH	LE	Q	1.4 3.9	1.5	3.8	ns	
t _{PHL}		Q	1.4 4.6	1.5	4.5	115	
^t PZH	OE	Q	1.7 4.4	1.8	4.3	ns	
t _{PZL}	OE OE	Q .	1,4 4.1	1.5	4	115	
^t PHZ	OE	Q	1.4 4.7	1.5	4.6	ns	
t _{PLZ}]		1 3.7	1	3.6	113	

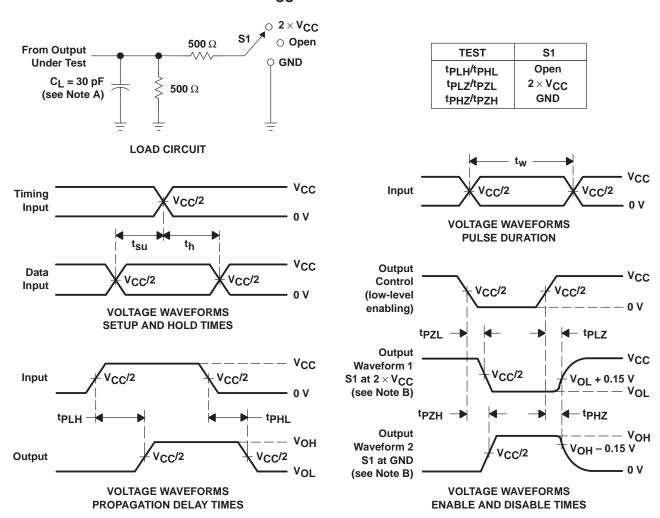
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	SN54ALVTH16373	SN74ALVTH16373	UNIT	
FARAIMETER	(INPUT)	(OUTPUT)	MIN MAX	MIN MAX	וואט	
tPLH	5	Q	1 3.2	1 3.1		
^t PHL	D	ď	1 3.4	1 3.3	ns	
^t PLH	LE	Q	1 3.4	1 3.3	ns	
^t PHL	LE	ď	1 3.6	1 3.5	115	
^t PZH	ŌĒ	Q	1.3 4.1	1.4 4	ns	
^t PZL	OE	ď	3.5	1 3.4	115	
^t PHZ	ŌĒ	Q	1.4 5	1.5 4.9	ne	
t _{PLZ}	OE	3	1.4 4.6	1.5 4.5	4.5 ns	



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PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



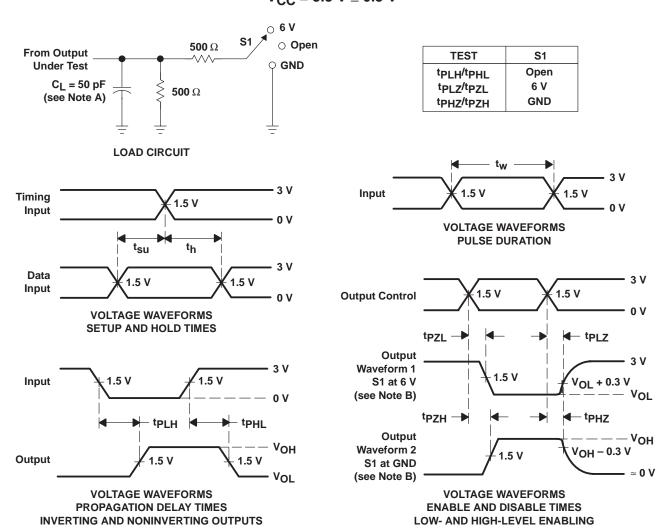
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2$ ns, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform22 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74ALVTH16373VRG4	ACTIVE	TVSOP	DGV	48	2000	TBD	Call TI	Call TI	-40 to 85		Samples
SN74ALVTH16373DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
SN74ALVTH16373DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
SN74ALVTH16373GR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
SN74ALVTH16373VR	ACTIVE	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	VT373	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVTH16373DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ALVTH16373GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ALVTH16373VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type		Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
SN74ALVTH16373DLR	SSOP	DL	48	1000	367.0	367.0	55.0	
SN74ALVTH16373GR	TSSOP	DGG	48	2000	367.0	367.0	45.0	
SN74ALVTH16373VR	TVSOP	DGV	48	2000	356.0	356.0	35.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type Pins		SPQ	L (mm)	W (mm)	T (µm)	B (mm)	
SN74ALVTH16373DL	DL	SSOP	48	25	473.7	14.24	5110	7.87	

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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